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NAME OF INVENTOR(S): Sheperck	
RECEIPT DATE & SERIAL NO.: <b>Serial No.: 10/736,661</b> Filing Date: 12/16/2003	
TITLE OF INVENTION: TEMPERATURE COMPENSATION SYSTEMS AND METHODS FOR USE WITH READ/WRITE HEADS IN MAGNETIC STORAGE DEVICES	
TI FILE NO.: <b>TI-36723</b>	DEPOSIT ACCT. NO.: <b>20-0668</b>
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